

PHP18NQ11T

N-channel TrenchMOS standard level FET

Rev. 02 — 10 March 2010

Product data sheet

1. Product profile

1.1 General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

1.2 Features and benefits

- Higher operating power due to low thermal resistance
- Suitable for high frequency applications due to fast switching characteristics

1.3 Applications

- Class-D audio amplifiers
- DC-to-DC convertors
- Inverters
- Switched-mode power supplies

1.4 Quick reference data

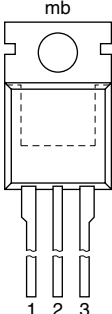
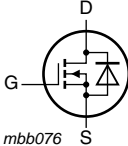
Table 1. Quick reference

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|--|-----|-----|-----|------------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$ | - | - | 110 | V |
| I_D | drain current | $T_{mb} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$; see Figure 1 and 3 | - | - | 18 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$; see Figure 2 | - | - | 79 | W |
| Dynamic characteristics | | | | | | |
| Q_{GD} | gate-drain charge | $V_{GS} = 10\text{ V}$; $I_D = 18\text{ A}$; $V_{DS} = 80\text{ V}$; $T_j = 25\text{ °C}$; see Figure 11 | - | 8 | - | nC |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10\text{ V}$; $I_D = 9\text{ A}$; $T_j = 25\text{ °C}$; see Figure 9 and 10 | - | 80 | 90 | m Ω |



2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------------------------|--|---|
| 1 | G | gate |  |  |
| 2 | D | drain | | |
| 3 | S | source | | |
| mb | D | mounting base; connected to drain | | |

SOT78 (TO-220AB)

3. Ordering information

Table 3. Ordering information

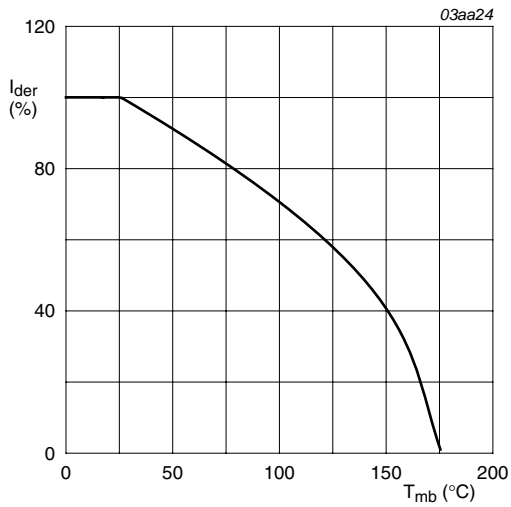
| Type number | Package | | |
|-------------|----------|--|---------|
| | Name | Description | Version |
| PHP18NQ11T | TO-220AB | plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB | SOT78 |

4. Limiting values

Table 4. Limiting values

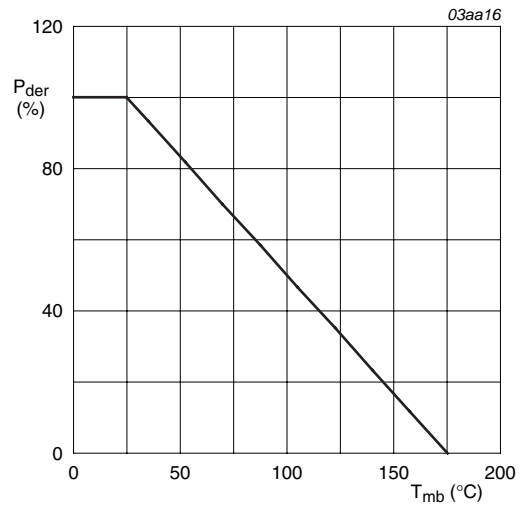
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------------|--|--|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$ | - | 110 | V |
| V_{DGR} | drain-gate voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$ | - | 110 | V |
| V_{GS} | gate-source voltage | | -20 | 20 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}$; $T_{mb} = 100\text{ °C}$; see Figure 1 | - | 13 | A |
| | | $V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; see Figure 1 and 3 | - | 18 | A |
| I_{DM} | peak drain current | $t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ °C}$; see Figure 3 | - | 72 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$; see Figure 2 | - | 79 | W |
| T_{stg} | storage temperature | | -55 | 175 | °C |
| T_j | junction temperature | | -55 | 175 | °C |
| Source-drain diode | | | | | |
| I_S | source current | $T_{mb} = 25\text{ °C}$ | - | 18 | A |
| I_{SM} | peak source current | $t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ °C}$ | - | 72 | A |
| Avalanche ruggedness | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ °C}$; $I_D = 11\text{ A}$; $V_{sup} \leq 25\text{ V}$; unclamped; $t_p = 0.1\text{ ms}$; $R_{GS} = 50\text{ }\Omega$ | - | 70 | mJ |



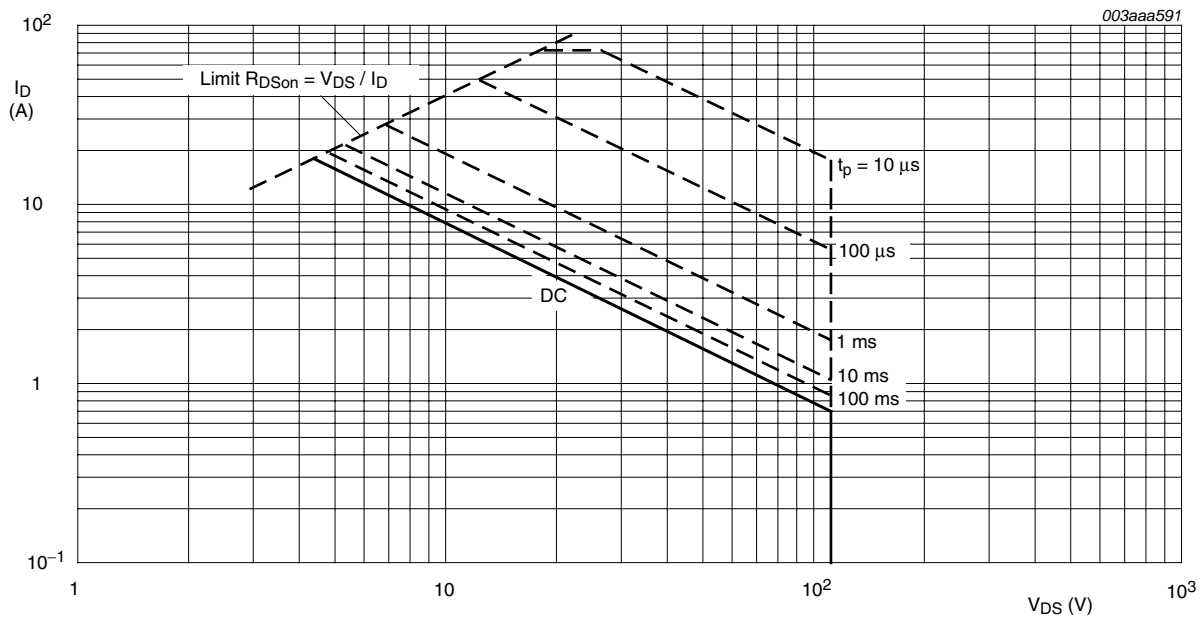
$$I_{der} = \frac{I_D}{I_{D(25^\circ C)}} \times 100\%$$

Fig 1. Normalized continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$T_{mb} = 25^\circ C; I_{DM}$ is single pulse; $V_{GS} = 10V$

Fig 3. Safe operating area: continuous and peak currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---|------------------------------|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | see Figure 4 | - | - | 1.9 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | - | 60 | - | K/W |

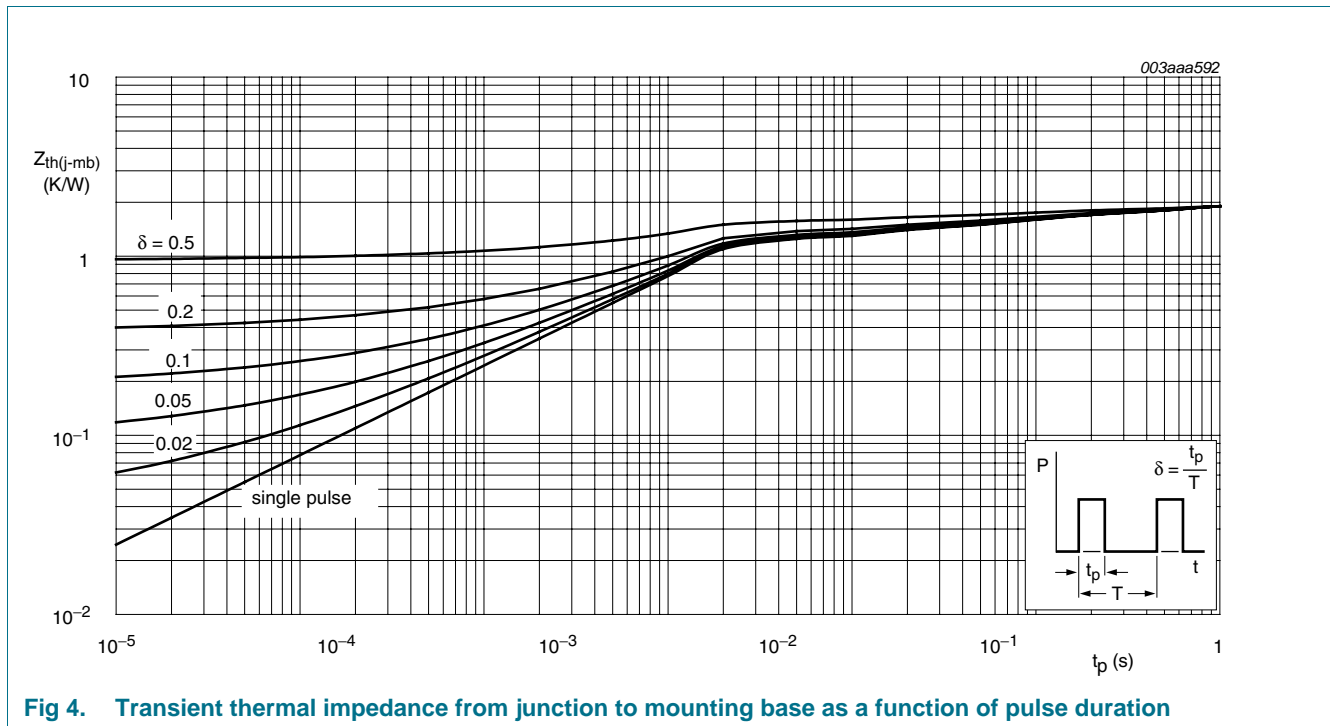
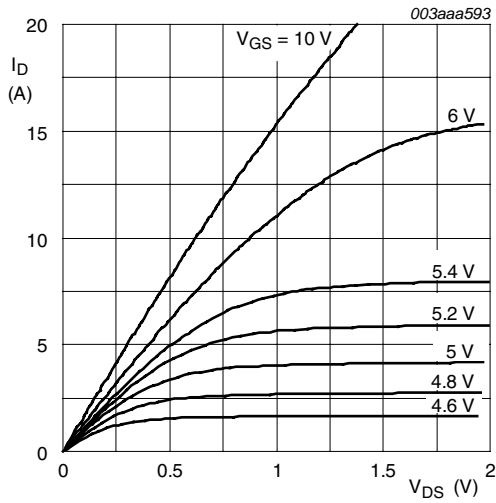


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

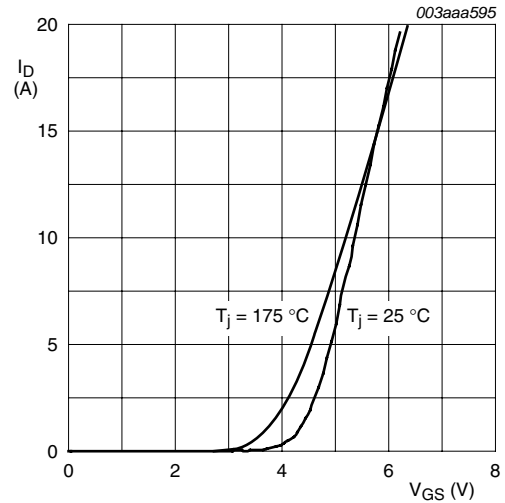
Table 6. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|--|-----|------|-----|------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$ | 98 | - | - | V |
| | | $I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | 110 | - | - | V |
| $V_{GS(th)}$ | gate-source threshold voltage | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ C$; see Figure 8 | 1 | - | - | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ C$; see Figure 8 | 2 | 3 | 4 | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ C$; see Figure 8 | - | - | 4.4 | V |
| I_{DSS} | drain leakage current | $V_{DS} = 110 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | 0.05 | 10 | μA |
| | | $V_{DS} = 110 V; V_{GS} = 0 V; T_j = 175 \text{ }^\circ C$ | - | - | 500 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | 10 | 100 | nA |
| | | $V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | 10 | 100 | nA |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10 V; I_D = 9 A; T_j = 175 \text{ }^\circ C$; see Figure 9 and 10 | - | - | 243 | m Ω |
| | | $V_{GS} = 10 V; I_D = 9 A; T_j = 25 \text{ }^\circ C$; see Figure 9 and 10 | - | 80 | 90 | m Ω |
| Dynamic characteristics | | | | | | |
| $Q_{G(tot)}$ | total gate charge | $I_D = 18 A; V_{DS} = 80 V; V_{GS} = 10 V; T_j = 25 \text{ }^\circ C$; see Figure 11 | - | 21 | - | nC |
| Q_{GS} | gate-source charge | | - | 4 | - | nC |
| Q_{GD} | gate-drain charge | | - | 8 | - | nC |
| C_{iss} | input capacitance | $V_{DS} = 25 V; V_{GS} = 0 V; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$; see Figure 12 | - | 633 | - | pF |
| C_{oss} | output capacitance | | - | 103 | - | pF |
| C_{rss} | reverse transfer capacitance | | - | 61 | - | pF |
| $t_{d(on)}$ | turn-on delay time | $V_{DS} = 50 V; R_L = 2.7 \text{ } \Omega; V_{GS} = 10 V; R_{G(ext)} = 5.6 \text{ } \Omega; T_j = 25 \text{ }^\circ C; I_D = 18.5 A$ | - | 6 | - | ns |
| t_r | rise time | | - | 36 | - | ns |
| $t_{d(off)}$ | turn-off delay time | | - | 18 | - | ns |
| t_f | fall time | | - | 12 | - | ns |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = 18 A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$; see Figure 13 | - | 0.92 | 1.2 | V |
| t_{rr} | reverse recovery time | $I_S = 18 A; di_S/dt = 100 A/\mu s; V_{GS} = 0 V; V_{DS} = 25 V; T_j = 25 \text{ }^\circ C$ | - | 55 | - | ns |
| Q_r | recovered charge | | - | 135 | - | nC |



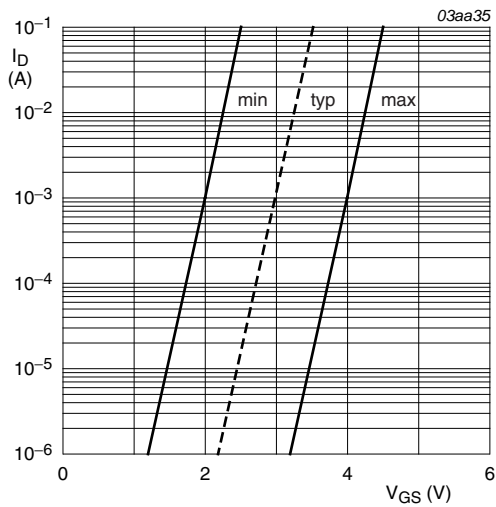
$T_j = 25^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



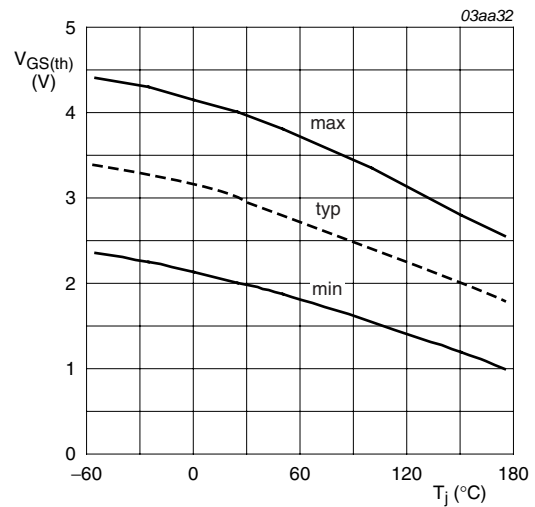
$T_j = 25^\circ\text{C}$ and $175^\circ\text{C}; V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values



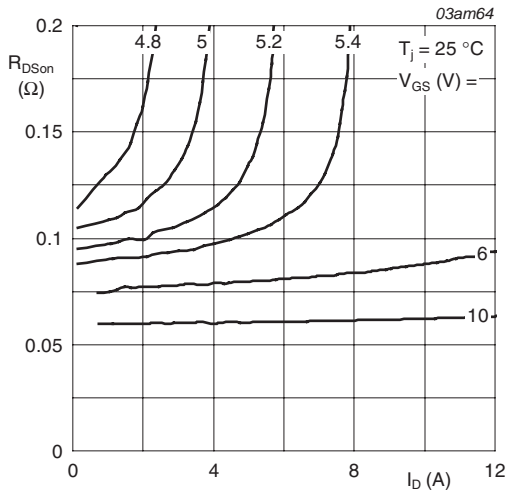
$T_j = 25^\circ\text{C}; V_{DS} = 5\text{ V}$

Fig 7. Sub-threshold drain current as a function of gate-source voltage



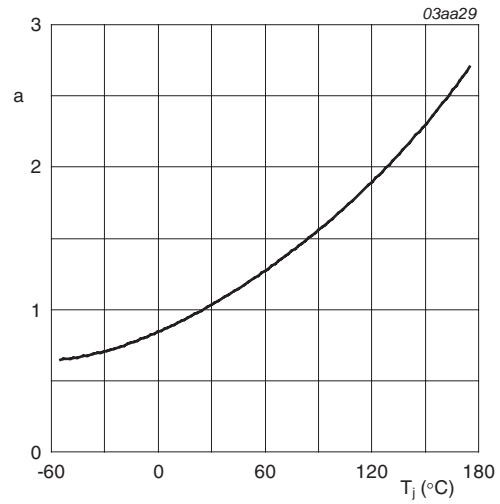
$I_D = 1\text{ mA}; V_{DS} = V_{GS}$

Fig 8. Gate-source threshold voltage as a function of junction temperature



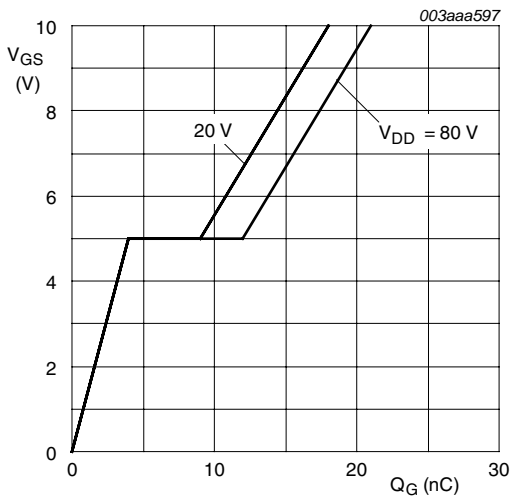
$T_j = 25^\circ\text{C}$

Fig 9. Drain-source on-state resistance as a function of drain current; typical values



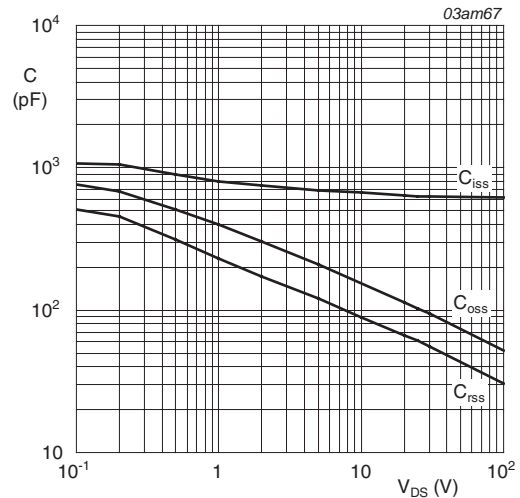
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 10. Normalized drain-source on-state resistance factor as a function of junction temperature



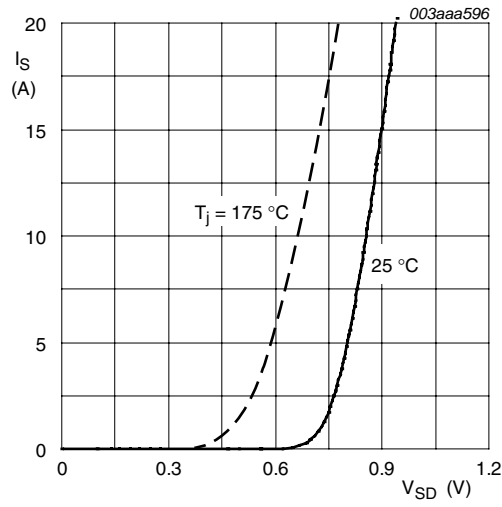
$I_D = 3\text{A}; V_{DD} = 20\text{V and } 80\text{V}$

Fig 11. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{V}; f = 1\text{MHz}$

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$T_j = 25^\circ\text{C}$ and $175^\circ\text{C}; V_{GS} = 0\text{V}$

Fig 13. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78

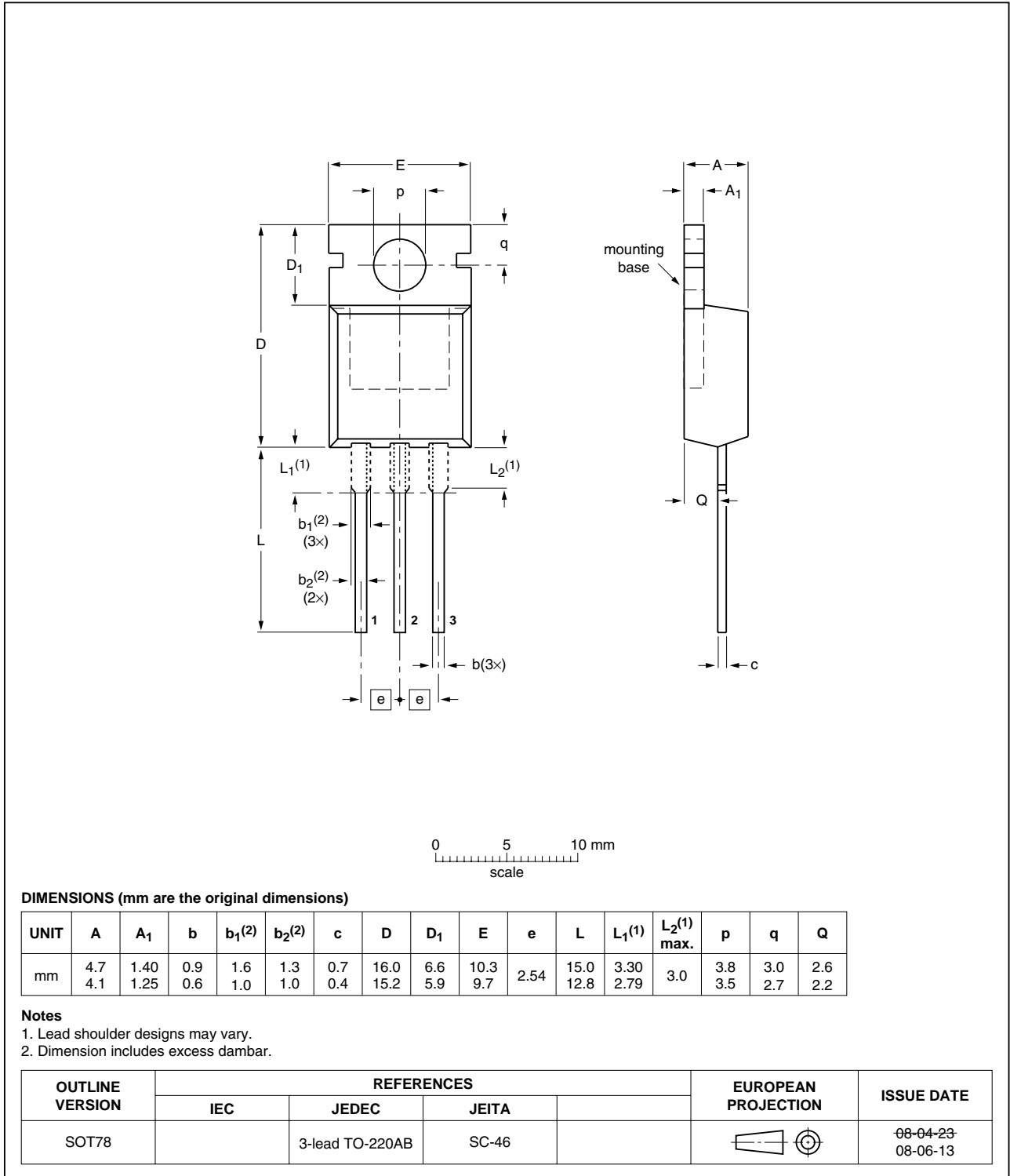


Fig 14. Package outline SOT78 (TO-220AB)

8. Revision history

Table 7. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|--------------------------------|--------------|--------------------|--|---------------|
| PHP18NQ11T_2 | 20100310 | Product data sheet | - | PHP18NQ11T-01 |
| Modifications: | | | | |
| | | | <ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate. | |
| PHP18NQ11T-01 (9397 750 12305) | 20031113 | Product data | - | - |

9. Legal information

9.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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